

# DATA SHEET

## **PCK2001M**

14.318-150 MHz I<sup>2</sup>C 1:10 Clock Buffer

Product specification  
Supersedes data of 1998 Oct 27

1999 Jul 06

14.318–150 MHz I<sup>2</sup>C 1:10 Clock Buffer

## PCK2001M

## FEATURES

- Mobile (reduced pincount) version of PCK2001
- Typically used to two SDRAM DIMMs
- 28 pin SSOP package
- Same general features as PCK2001
- See PCK2001 for 48-pin 1-18 buffer part supporting up to 4 SDRAM DIMMs
- Optimized for 66MHz, 100MHz and 133MHz operation

- 175 ps skew outputs
- Individual clock output enable/disable via I<sup>2</sup>C

## DESCRIPTION

The PCK2001M is a 1–10 fanout buffer used for 133/100 MHz CPU, 66/33 MHz PCI, 14.318 MHz REF, or 133/100/66 MHz SDRAM clock distribution. 10 outputs are typically used to support up to 2 SDRAM DIMMs commonly found in laptop or mobile applications. The PCK2001M has the same features and operating characteristics of the PCK2001 and is available in the SSOP 28 pin package.

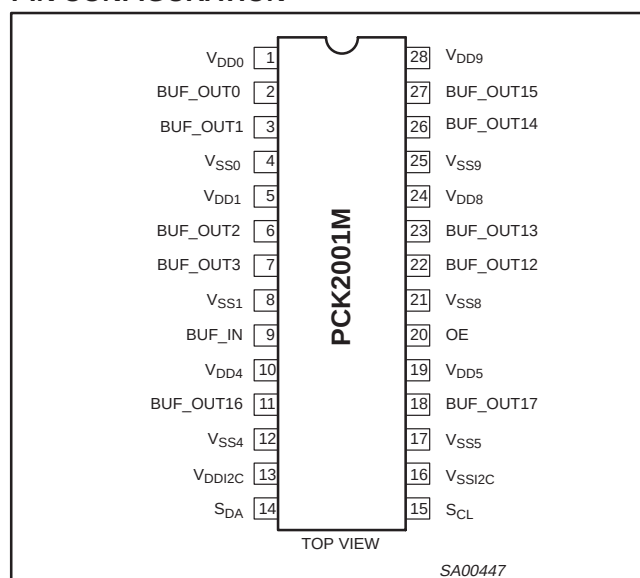
## QUICK REFERENCE DATA

| SYMBOL                 | PARAMETER                                           | CONDITIONS                  | TYPICAL    | UNIT |
|------------------------|-----------------------------------------------------|-----------------------------|------------|------|
| $t_{PLH}$<br>$t_{PHL}$ | Propagation delay<br>BUF_IN to BUF_OUT <sub>n</sub> | $V_{CC} = 3.3V$ , CL = 30pF | 2.5<br>2.5 | ns   |
| $t_r$                  | Rise time                                           | $V_{CC} = 3.3V$ , CL = 30pF | 1.0        | ns   |
| $t_f$                  | Fall time                                           | $V_{CC} = 3.3V$ , CL = 20pF | 700        | ps   |
| $I_{CC}$               | Total supply current                                | $V_{CC} = 3.465V$           | 50         | μA   |

## ORDERING INFORMATION

| PACKAGES            | TEMPERATURE RANGE | ORDER CODE  | DRAWING NUMBER |
|---------------------|-------------------|-------------|----------------|
| 28-Pin Plastic SSOP | 0°C to +70°C      | PCK2001M DB | SOT341–1       |

## PIN CONFIGURATION



## PIN DESCRIPTION

| PIN NUMBER           | I/O TYPE | SYMBOL          | FUNCTION                           |
|----------------------|----------|-----------------|------------------------------------|
| 2, 3, 6, 7           | Output   | BUF_OUT (0–3)   | Buffered clock outputs             |
| 22, 23, 26, 27       | Output   | BUF_OUT (12–15) | Buffered clock outputs             |
| 11, 18               | Output   | BUF_OUT (16–17) | Buffered clock outputs             |
| 9                    | Input    | BUF_IN          | Buffered clock input               |
| 20                   | Input    | OE              | Active high output enable          |
| 14                   | I/O      | SDA             | I <sup>2</sup> C serial data       |
| 15                   | Input    | SCL             | I <sup>2</sup> C serial clock      |
| 1, 5, 10, 19, 24, 28 | Input    | $V_{DD}$ (0–9)  | 3.3V power supply                  |
| 4, 8, 12, 17, 21, 25 | Input    | $V_{SS}$ (0–9)  | Ground                             |
| 13                   | Input    | $V_{DDI2C}$     | 3.3V I <sup>2</sup> C power supply |
| 16                   | Input    | $V_{DDI2C}$     | I <sup>2</sup> C ground            |

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I<sup>2</sup>C is a trademark of Philips Semiconductors Corporation.

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## FUNCTION TABLE

| OE | BUF_IN | I <sup>2</sup> CEN | BUF_OUTn |
|----|--------|--------------------|----------|
| L  | X      | X                  | Z        |
| H  | L      | X                  | L        |
| H  | H      | H                  | H        |
| H  | H      | L                  | L        |

ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

In accordance with the Absolute Maximum Rating System (IEC 134)

Voltages are referenced to V<sub>SS</sub> (V<sub>SS</sub> = 0V)

| SYMBOL           | PARAMETER                                                        | CONDITION                                                                      | LIMITS |                       | UNIT |
|------------------|------------------------------------------------------------------|--------------------------------------------------------------------------------|--------|-----------------------|------|
|                  |                                                                  |                                                                                | MIN    | MAX                   |      |
| V <sub>DD</sub>  | DC 3.3V supply voltage                                           |                                                                                | −0.5   | +4.6                  | V    |
| I <sub>IK</sub>  | DC input diode current                                           | V <sub>I</sub> < 0                                                             |        | −50                   | mA   |
| V <sub>I</sub>   | DC input voltage                                                 | Note 2                                                                         | −0.5   | 5.5                   | V    |
| I <sub>OK</sub>  | DC output diode current                                          | V <sub>O</sub> > V <sub>DD</sub> or V <sub>O</sub> < 0                         |        | ±50                   | mA   |
| V <sub>O</sub>   | DC output voltage                                                | Note 2                                                                         | −0.5   | V <sub>CC</sub> + 0.5 | V    |
| I <sub>O</sub>   | DC output source or sink current                                 | V <sub>O</sub> ≥ 0 to V <sub>DD</sub>                                          |        | ±50                   | mA   |
| T <sub>STG</sub> | Storage temperature range                                        |                                                                                | −65    | +150                  | °C   |
| P <sub>TOT</sub> | Power dissipation per package<br>plastic medium-shrink SO (SSOP) | For temperature range: 0 to +70°C<br>above +55°C derate linearly with 11.3mW/K |        | 850                   | mW   |

## NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## RECOMMENDED OPERATING CONDITIONS

| SYMBOL           | PARAMETER                                       | CONDITIONS | LIMITS |                 | UNIT |
|------------------|-------------------------------------------------|------------|--------|-----------------|------|
|                  |                                                 |            | MIN    | MAX             |      |
| V <sub>DD</sub>  | DC 3.3V supply voltage                          |            | 3.135  | 3.465           | V    |
| C <sub>L</sub>   | Capacitive load                                 |            | 20     | 30              | pF   |
| V <sub>I</sub>   | DC input voltage range                          |            | 0      | V <sub>DD</sub> | V    |
| V <sub>O</sub>   | DC output voltage range                         |            | 0      | V <sub>DD</sub> | V    |
| T <sub>amb</sub> | Operating ambient temperature range in free air |            | 0      | +70             | °C   |

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## DC CHARACTERISTICS

| SYMBOL                 | PARAMETER                                                 | TEST CONDITIONS     |                                              |                    | LIMITS                                                       |                       | UNIT          |
|------------------------|-----------------------------------------------------------|---------------------|----------------------------------------------|--------------------|--------------------------------------------------------------|-----------------------|---------------|
|                        |                                                           |                     |                                              |                    | $T_{\text{amb}} = 0^{\circ}\text{C to } +70^{\circ}\text{C}$ |                       |               |
|                        |                                                           | $V_{\text{DD}}$ (V) | OTHER                                        |                    | MIN                                                          | MAX                   |               |
| $V_{\text{IH}}$        | HIGH level input voltage                                  | 3.135 to 3.465      |                                              |                    | 2.0                                                          | $V_{\text{DD}} + 0.3$ | V             |
| $V_{\text{IL}}$        | LOW level input voltage                                   | 3.135 to 3.465      |                                              |                    | $V_{\text{SS}} - 0.3$                                        | 0.8                   | V             |
| $V_{\text{OH}}$        | 3.3V output HIGH voltage                                  | 3.135 to 3.465      | $I_{\text{OH}} = -1\text{mA}$                |                    | 2.4                                                          | –                     | V             |
| $V_{\text{OL}}$        | 3.3V output LOW voltage                                   | 3.135 to 3.465      | $I_{\text{OL}} = 1\text{mA}$                 |                    | –                                                            | 0.4                   | V             |
| $I_{\text{OH}}$        | Output HIGH current                                       | 3.135 to 3.465      | $V_{\text{OUT}} = 2.0\text{V}$               |                    | –54                                                          | –                     | mA            |
|                        |                                                           | 3.135 to 3.465      | $V_{\text{OUT}} = 3.135\text{V}$             |                    | –                                                            | –46                   |               |
| $I_{\text{OL}}$        | Output LOW current                                        | 3.135 to 3.465      | $V_{\text{OUT}} = 1.0\text{V}$               |                    | 54                                                           | –                     | mA            |
|                        |                                                           | 3.135 to 3.465      | $V_{\text{OUT}} = 0.4\text{V}$               |                    | –                                                            | 53                    |               |
| $\pm I_{\text{I}}$     | Input leakage current                                     | 3.465               |                                              |                    | –                                                            | 5                     | $\mu\text{A}$ |
| $\pm I_{\text{OZ}}$    | 3-State output OFF-State current                          | 3.465               | $V_{\text{OUT}} = V_{\text{DD}}$ or GND      | $I_{\text{O}} = 0$ | –                                                            | 10                    | $\mu\text{A}$ |
| $I_{\text{CC}}$        | Quiescent supply current                                  | 3.465               | $V_{\text{I}} = V_{\text{DD}}$ or GND        | $I_{\text{O}} = 0$ | –                                                            | 100                   | $\mu\text{A}$ |
| $\Delta I_{\text{CC}}$ | Additional quiescent supply current given per control pin | 3.135 to 3.465      | $V_{\text{I}} = V_{\text{DD}} - 0.6\text{V}$ | $I_{\text{O}} = 0$ | –                                                            | 500                   | $\mu\text{A}$ |

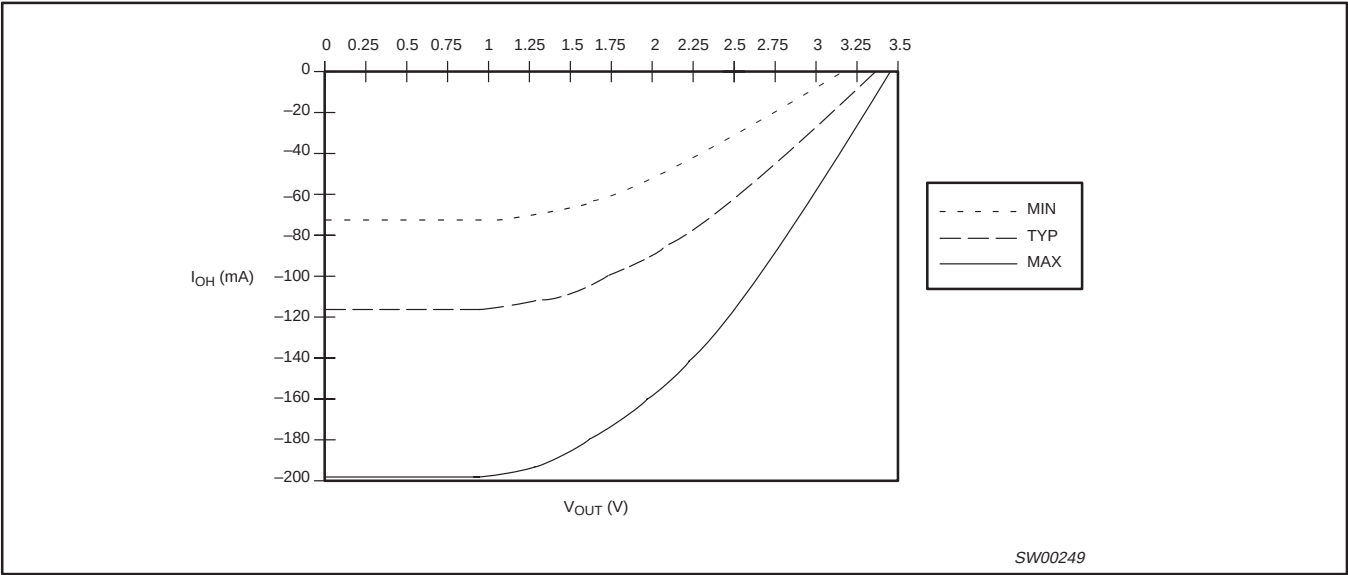
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SDRAM CLOCK OUTPUT BUFFER PULL-UP CHARACTERISTICS

| PULL-UP        |           |      |      |
|----------------|-----------|------|------|
| VOLTAGE<br>(V) | I<br>(mA) |      |      |
|                | MIN       | TYP  | MAX  |
| 0              | −72       | −116 | −198 |
| 1              | −72       | −116 | −198 |
| 1.40           | −68       | −110 | −188 |
| 1.50           | −67       | −107 | −184 |
| 1.65           | −64       | −103 | −177 |
| 1.80           | −60       | −98  | −170 |
| 2.00           | −54       | −90  | −157 |
| 2.40           | −39       | −69  | −126 |
| 2.60           | −30       | −56  | −107 |
| 3.135          | 0         | −15  | −46  |
| 3.30           |           | 0    | −23  |
| 3.465          |           |      | 0    |

SDRAM PULL-UP



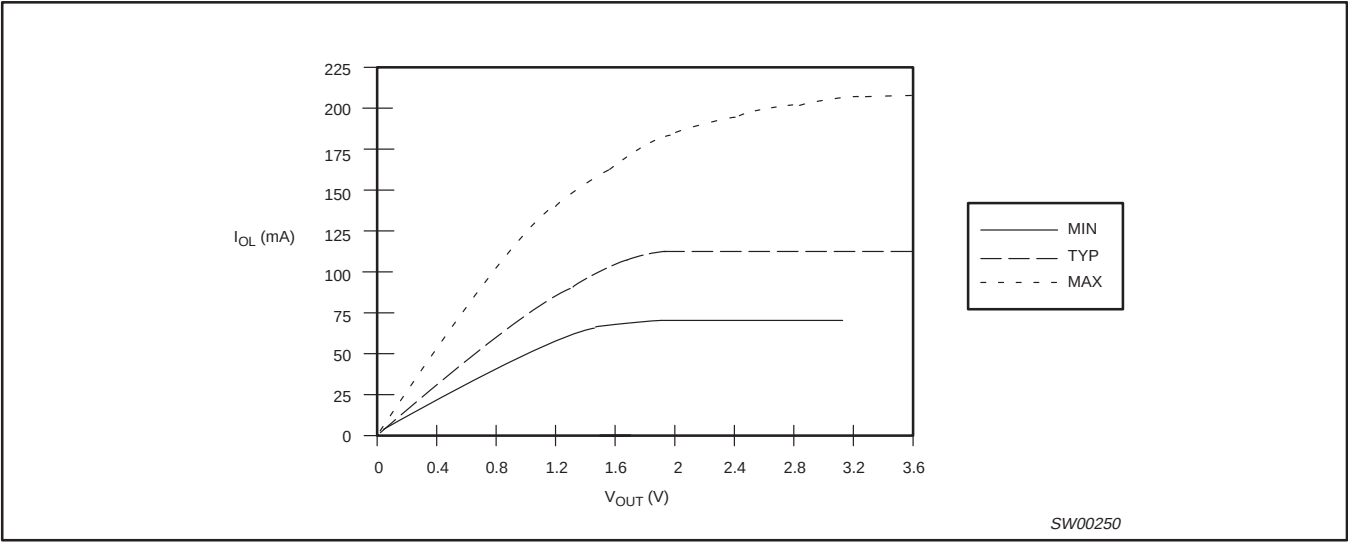
14.318–150 MHz I<sup>2</sup>C 1:10 Clock Buffer

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SDRAM CLOCK OUTPUT BUFFER PULL-DOWN CHARACTERISTICS

| PULL-UP        |           |     |     |
|----------------|-----------|-----|-----|
| VOLTAGE<br>(V) | I<br>(mA) |     |     |
|                | MIN       | TYP | MAX |
| 0              | 0         | 0   | 0   |
| 0.4            | 23        | 34  | 53  |
| 0.65           | 35        | 52  | 83  |
| 0.85           | 43        | 65  | 104 |
| 1.00           | 49        | 74  | 118 |
| 1.4            | 61        | 93  | 152 |
| 1.5            | 64        | 98  | 159 |
| 1.65           | 67        | 103 | 168 |
| 1.8            | 70        | 108 | 177 |
| 1.95           | 72        | 112 | 184 |
| 3.135          | 72        | 112 | 204 |
| 3.6            |           | 112 | 204 |

SDRAM PULL-DOWN



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## AC CHARACTERISTICS

| SYMBOL                              | PARAMETER                         | TEST CONDITIONS  |          | LIMITS<br>T <sub>amb</sub> = 0°C to +70°C |                  |      | UNIT |
|-------------------------------------|-----------------------------------|------------------|----------|-------------------------------------------|------------------|------|------|
|                                     |                                   |                  | NOTES    | MIN                                       | TYP <sup>9</sup> | MAX  |      |
| T <sub>SDKP</sub>                   | SDRAM CLK period                  | 66MHz            | 1, 6     | 15.0                                      | 15.2             | 15.5 | ns   |
| T <sub>SDKH</sub>                   | SDRAM CLK HIGH time               |                  | 2, 6, 8  | 5.6                                       | 7.8              | 8.4  |      |
| T <sub>SDKL</sub>                   | SDRAM CLK LOW time                |                  | 3, 6, 8  | 5.3                                       | 7.4              | 8.0  |      |
| T <sub>SDKP</sub>                   | SDRAM CLK period                  | 100MHz           | 1, 6     | 10.0                                      | 10.01            | 10.5 | ns   |
| T <sub>SDKH</sub>                   | SDRAM CLK HIGH time               |                  | 2, 6, 8  | 3.3                                       | 5.1              | 5.7  |      |
| T <sub>SDKL</sub>                   | SDRAM CLK LOW time                |                  | 3, 6, 8  | 3.1                                       | 4.9              | 5.5  |      |
| T <sub>SDKP</sub>                   | SDRAM CLK period                  | 133MHz           | 1, 6     | 7.4                                       | 7.5              | 7.7  | ns   |
| T <sub>SDKH</sub>                   | SDRAM CLK HIGH time               |                  | 2, 6, 8  | 2.6                                       | 3.2              | 3.8  |      |
| T <sub>SDKL</sub>                   | SDRAM CLK LOW time                |                  | 3, 6, 8  | 2.1                                       | 2.8              | 3.5  |      |
| T <sub>SDRISE</sub>                 | SDRAM rise time                   |                  | 4, 6, 10 | 1.5                                       | 2.0              | 4.0  | V/ns |
| T <sub>SDFALL</sub>                 | SDRAM fall time                   |                  | 4, 6, 11 | 1.5                                       | 2.9              | 4.0  | V/ns |
| T <sub>PLH</sub>                    | SDRAM buffer LH propagation delay |                  | 6, 7     | 1.0                                       | 2.5              | 3.5  | ns   |
| T <sub>PHL</sub>                    | SDRAM buffer HL propagation delay |                  | 6, 7     | 1.0                                       | 2.5              | 3.5  | ns   |
| T <sub>PZL</sub> , T <sub>PZH</sub> | SDRAM buffer enable time          |                  | 6, 7     | 1.0                                       | 2.6              | 5.0  | ns   |
| T <sub>PLZ</sub> , T <sub>PHZ</sub> | SDRAM buffer disable time         |                  | 6, 7     | 1.0                                       | 2.7              | 5.0  | ns   |
| DUTY CYCLE                          | Output Duty Cycle                 | Measured at 1.5V | 5, 6, 7  | 45                                        | 52               | 55   | %    |
| T <sub>SDSKW</sub>                  | SDRAM Bus CLK skew                |                  | 1, 6     |                                           | 150              | 250  | ps   |
| T <sub>DDSKW</sub>                  | Device to device skew             |                  |          |                                           |                  | 250  | ps   |

## NOTES:

1. Clock period and skew are measured on the rising edge at 1.5V.
2. T<sub>SDKH</sub> is measured at 2.4V as shown in Figure 4.
3. T<sub>SDKL</sub> is measured at 0.4V as shown in Figure 4.
4. T<sub>SDRISE</sub> and T<sub>SDFALL</sub> are measured as a transition through the threshold region V<sub>OL</sub> = 0.4V and V<sub>OH</sub> = 2.4V (1mA) JEDEC specification.
5. Duty cycle should be tested with a 50/50% input.
6. Over MIN (20pF) to MAX (30pF) discrete load, process, voltage, and temperature.
7. Input edge rate for these tests must be faster than 1 V/ns.
8. Calculated at minimum edge rate (1.5ns) to guarantee 45/55% duty cycle at 1.5V. Pulswidth is required to be wider at the faster edge to ensure duty cycle specification is met.
9. All typical values are at V<sub>CC</sub> = 3.3V and T<sub>amb</sub> = 25°C.
10. Typical is measured with MAX (30pf) discrete load.
11. Typical is measured with MIN (20pf) discrete load.

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I<sup>2</sup>C CONSIDERATIONS

I<sup>2</sup>C has been chosen as the serial bus interface to control the PCK2001M. I<sup>2</sup>C was chosen to support the JEDEC proposal JC-42.5 168 Pin Unbuffered SDRAM DIMM. All vendors are required to determine the legal issues associated with the manufacture of I<sup>2</sup>C devices.

1) Address assignment: The clock driver in this specification uses the single, 7-bit address shown below. All devices can use the address if only one master clock driver is used in a design. The address can be re-used for the CKBF device if no other conflicting I<sup>2</sup>C clock driver is used in the system.

The following address was confirmed by Philips on 09/04/96.

| A6 | A5 | A4 | A3 | A2 | A1 | A0 | R/W# |
|----|----|----|----|----|----|----|------|
| 1  | 1  | 0  | 1  | 0  | 0  | 1  | 0    |

**NOTE:** The R/W# bit is used by the I<sup>2</sup>C controller as a data direction bit. A 'zero' indicates a transmission (WRITE) to the clock device. A 'one' indicates a request for data (READ) from the clock driver. Since the definition of the clock buffer only allows the controller to WRITE data; the R/W# bit of the address will always be seen as 'zero'. Optimal address decoding of this bit is left to the vendor.

2) Options: It is our understanding that metal mask options and other pinouts of this type of clock driver will be allowed to use the same address as the original CKBF device. I<sup>2</sup>C addresses are defined in terms of function (master clock driver) rather than form (pinout, and option).

3) Slave/Receiver: The clock driver is assumed to require only slave/receiver functionality. Slave/transmitter functionality is optional.

4) Data Transfer Rate: 100 kbits/s (standard mode) is the base functionality required. Fast mode (400 kbits/s) functionality is optional.

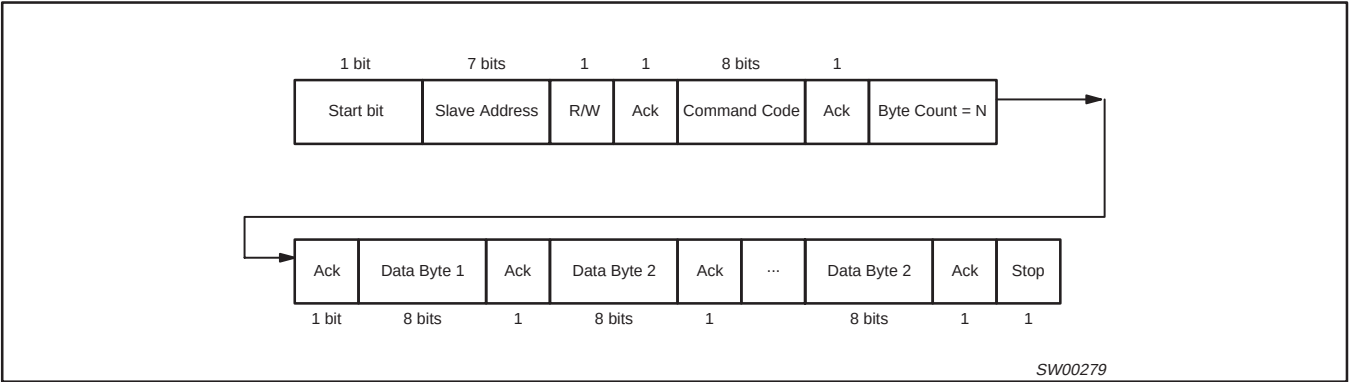
5) Logic Levels: I<sup>2</sup>C logic levels are based on a percentage of V<sub>DD</sub> for the controller and other devices on the bus. Assume all devices are based on a 3.3 Volt supply.

6) Data Byte Format: Byte format is 8 Bits as described in the following appendices.

7) Data Protocol: To simplify the clock I<sup>2</sup>C interface, the clock driver serial protocol was specified to use only block writes from the controller. The bytes must be accessed in sequential order from lowest to highest byte with the ability to stop after any complete byte has been transferred. Indexed bytes are not allowed. However, the SMBus controller has a more specific format than the generic I<sup>2</sup>C protocol.

The clock driver must meet this protocol which is more rigorous than previously stated I<sup>2</sup>C protocol. Treat the description from the viewpoint of controller. The controller “writes” to the clock driver and if possible would “read” from the clock driver (the clock driver is a slave/receiver only and is incapable of this transaction.)

“The block write begins with a slave address and a write condition. After the command code the host (controller) issues a byte count which describes how many more bytes will follow in the message. If the host had 20 bytes to send, the first byte would be the number 20 (14h), followed by the 20 bytes of data. The byte count may not be 0. A block write command is allowed to transfer a maximum of 32 data bytes.”



**NOTE:** The acknowledgement bit is returned by the slave/receiver (the clock driver).

Consider the command code and the byte count bytes required as the first two bytes of any transfer. The command code is software programmable via the controller, but will be specified as 0000 0000 in the clock specification. The byte count byte is the number of additional bytes required to transfer, not counting the command code and byte count bytes. Additionally, the byte count byte is required to be a minimum of 1 byte and a maximum of 32 bytes to satisfy the above requirement.



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For example:

| Byte count byte |      | Notes:                                                                       |
|-----------------|------|------------------------------------------------------------------------------|
| MSB             | LSB  |                                                                              |
| 0000            | 0000 | Not allowed. Must have at least one byte.                                    |
| 0000            | 0001 | Data for functional and frequency select register (currently byte 0 in spec) |
| 0000            | 0010 | Reads first two bytes of data. (byte 0 then byte 1)                          |
| 0000            | 0011 | Reads first three bytes (byte 0, 1, 2 in order)                              |
| 0000            | 0100 | Reads first four bytes (byte 0, 1, 2, 3 in order)                            |
| 0000            | 0101 | Reads first five bytes (byte 0, 1, 2, 3, 4 in order)                         |
| 0000            | 0110 | Reads first six bytes (byte 0, 1, 2, 3, 4, 5 in order)                       |
| 0000            | 0111 | Reads first seven bytes (byte 0, 1, 2, 3, 4, 5, 6 in order)                  |
| 0010            | 0000 | Max byte count supported = 32                                                |

A transfer is considered valid after the acknowledge bit corresponding to the byte count is read by the controller. The serial controller interface can be simplified by discarding the information in both the command code and the byte count bytes and simply reading all the bytes that are sent to the clock driver after being addressed by the controller. It is expected that the controller will not provide more bytes than the clock driver can handle. A clock vendor may choose to discard any number of bytes that exceed the defined byte count.

8) Clock stretching: The clock device must not hold/stretch the SCLOCK or SDATA lines low for more than 10 mS. Clock stretching is discouraged and should only be used as a last resort. Stretching the clock/data lines for longer than this time puts the device in an error/time-out mode and may not be supported in all platforms. It is assumed that all data transfers can be completed as specified without the use of clock/data stretching.

9) General Call: It is assumed that the clock driver will not have to respond to the "general call."

10) Electrical Characteristics: All electrical characteristics must meet the standard mode specifications found in section 15 of the I<sup>2</sup>C specification.

a) Pull-Up Resistors: Any internal resistors pull-ups on the SDATA and SCLOCK inputs must be stated in the individual datasheet. The use of internal pull-ups on these pins of below 100K is discouraged. Assume that the board designer will use a single external pull-up resistor for each line and that these values are in the 5 - 6K Ohm range. Assume one I<sup>2</sup>C device per DIMM (serial presence detect), one I<sup>2</sup>C controller, one clock driver plus one/two more I<sup>2</sup>C devices on the platform for capacitive loading purposes.

(b) Input Glitch Filters: Only fast mode I<sup>2</sup>C devices require input glitch filters to suppress bus noise. The clock driver is specified as a standard mode device and is not required to support this feature.

11) PWR DWN#: If a clock driver is placed in PWR DWN# mode, the SDATA and SCLK inputs must be Tri-Stated and the device must retain all programming information. I<sub>dd</sub> current due to the I<sup>2</sup>C circuitry must be characterized and in the data sheet.

For specific I<sup>2</sup>C information consult the Philips I<sup>2</sup>C Peripherals Data Handbook IC12 (1997)

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**SERIAL CONFIGURATION MAP**

The serial bits will be read by the clock buffer in the following order:

Byte 0 – Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte 1 – Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte 2 – Bits 7, 6, 5, 4, 3, 2, 1, 0

All unused register bits (Reserved and N/A) should be desined as “Dont Care”. It is expected that the controller will force all of these bits to a “0” level.

All register bits labeled “Initialize to 0” must be written to zero during intialization. Failure to do so may result in a higher than normal operating current. The controller will read back the last written value.

**Byte 0: Output active/inactive register**

1 = enable; 0 = disable

| BIT | PIN# | NAME     | DESCRIPTION     |
|-----|------|----------|-----------------|
| 7   | —    | BUF_OUT7 | Initialize to 0 |
| 6   | —    | BUF_OUT6 | Initialize to 0 |
| 5   | —    | BUF_OUT5 | Initialize to 0 |
| 4   | —    | BUF_OUT4 | Initialize to 0 |
| 3   | 7    | BUF_OUT3 | Active/Inactive |
| 2   | 6    | BUF_OUT2 | Active/Inactive |
| 1   | 3    | BUF_OUT1 | Active/Inactive |
| 0   | 2    | BUF_OUT0 | Active/Inactive |

**NOTE:**

1. Inactive means outputs are held LOW and are disabled from switching. These outputs are designed to be configured at power-on and are not expected to be configured during the normal modes of operation.

**Byte 1: Output active/inactive register**

1 = enable; 0 = disable

| BIT | PIN# | NAME      | DESCRIPTION     |
|-----|------|-----------|-----------------|
| 7   | 27   | BUF_OUT15 | Active/Inactive |
| 6   | 26   | BUF_OUT14 | Active/Inactive |
| 5   | 23   | BUF_OUT13 | Active/Inactive |
| 4   | 22   | BUF_OUT12 | Active/Inactive |
| 3   | —    | BUF_OUT11 | Initialize to 0 |
| 2   | —    | BUF_OUT10 | Initialize to 0 |
| 1   | —    | BUF_OUT9  | Initialize to 0 |
| 0   | —    | BUF_OUT8  | Initialize to 0 |

**NOTE:**

1. Inactive means outputs are held LOW and are disabled from switching. These outputs are designed to be configured at power-on and are not expected to be configured during the normal modes of operation.

**Byte 2: Optional register for possible future requirments**

| BIT | PIN# | NAME       | DESCRIPTION     |
|-----|------|------------|-----------------|
| 7   | 18   | BUF_OUT17  | Active/Inactive |
| 6   | 11   | BUF_OUT16  | Active/Inactive |
| 5   | —    | (reserved) | (reserved)      |
| 4   | —    | (reserved) | (reserved)      |
| 3   | —    | (reserved) | (reserved)      |
| 2   | —    | (reserved) | (reserved)      |
| 1   | —    | (reserved) | (reserved)      |
| 0   | —    | (reserved) | (reserved)      |

**NOTE:**

1. Inactive means outputs are held LOW and are disabled from switching. These outputs are designed to be configured at power-on and are not expected to be configured during the normal modes of operation.

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AC WAVEFORMS

$V_M = 1.5V$   
 $V_X = V_{OL} + 0.3V$   
 $V_Y = V_{OH} - 0.3V$   
 $V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.

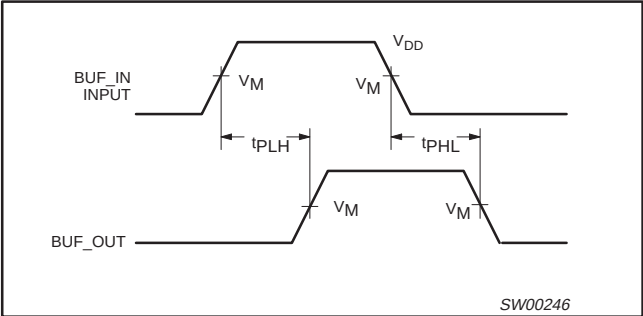


Figure 1. Load circuitry for switching times.

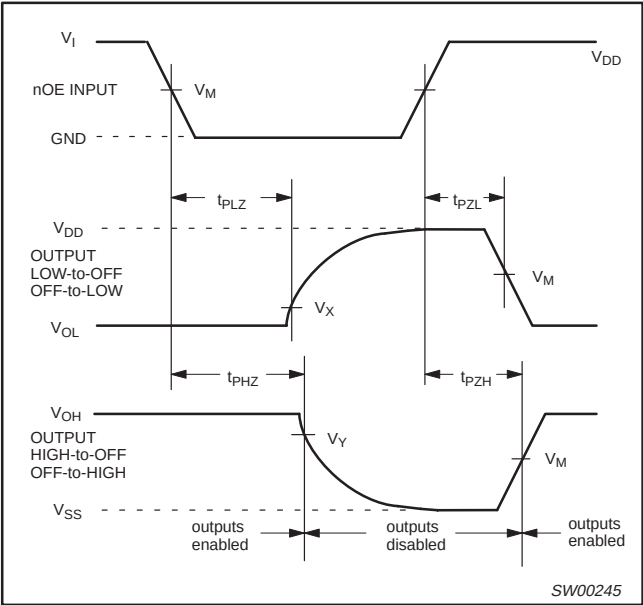


Figure 2. 3-State enable and disable times

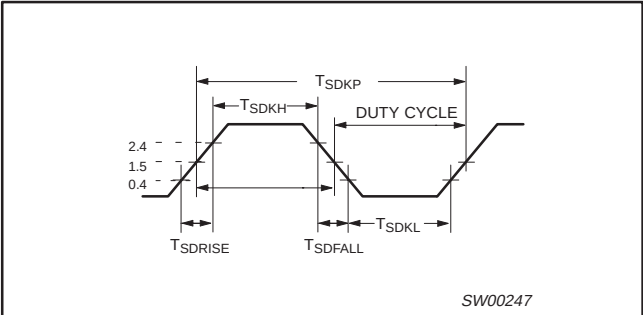


Figure 3. SDRAM Output clock

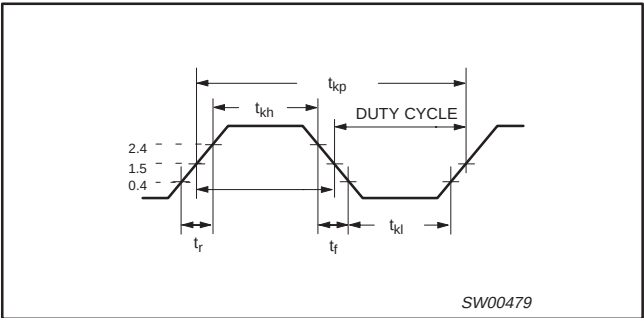


Figure 4. Buffer Output clock

TEST CIRCUIT

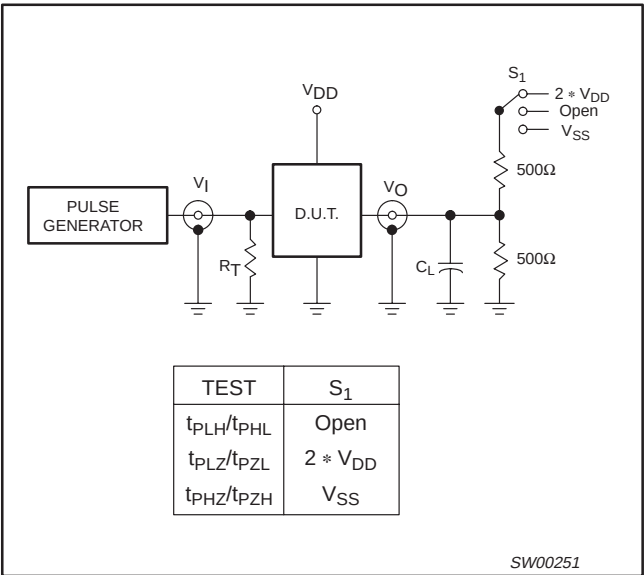


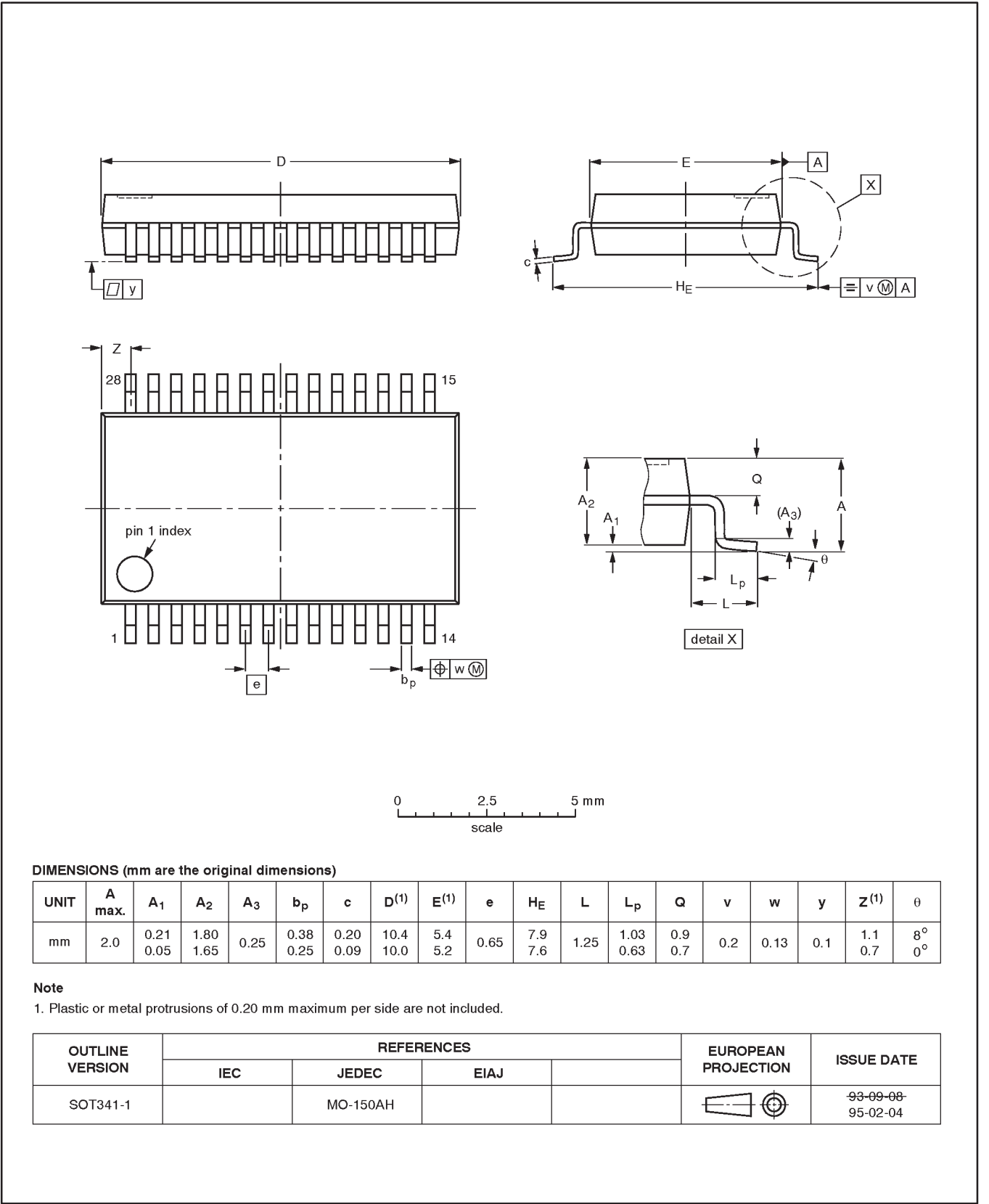
Figure 5. Load circuitry for switching times

14.318-150 MHz I<sup>2</sup>C 1:10 Clock Buffer

PCK2001M

SSOP28: plastic shrink small outline package; 28 leads; body width 5.3mm

SOT341-1



14.318-150 MHz I<sup>2</sup>C 1:10 Clock Buffer

PCK2001M

## Data sheet status

| Data sheet status         | Product status | Definition [1]                                                                                                                                                                                                                                             |
|---------------------------|----------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Objective specification   | Development    | This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.                                                                                                          |
| Preliminary specification | Qualification  | This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product. |
| Product specification     | Production     | This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.                                                       |

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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